		G. and Marit	DB I	Time stamp
L Number	Hits	Search Text		
1	591015	<pre>(plate or board or substrate or article) near5 (resin\$5 or polymer\$5 or plastic or polyimide or non\$2conduct\$8 or insulat\$8 or epoxy)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/03 10:46
2	129791	((plate or board or substrate or article) near5 (resin\$5 or polymer\$5 or plastic or polyimide or non\$2conduct\$8 or insulat\$8 or epoxy)) and ((plate or board or substrate or article) near5 (via\$3 or hole\$3 or opening\$3 or trench\$3.or	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 10: 4 7
3	10	recess\$3 or cavit\$6}) "13" and (electroless\$3 near15 (via\$3 or hole\$3 or opening\$3 or trench\$3 or recess\$3 or cavit\$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/03 10:53
4	1851	article) near5 (resin\$5 or polymer\$5 or plastic or polyimide or non\$2conduct\$8 or insulat\$8 or epoxy)) and ((plate or board or substrate or article) near5 (via\$3 or hole\$3 or opening\$3 or trench\$3 or recess\$3 or cavit\$6))) and (electroless\$3 near15 (via\$3 or hole\$3 or opening\$3 or trench\$3 or recess\$3 or cavit\$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 10:53
5	951	((((plate or board or substrate or article) near5 (resin\$5 or polymer\$5 or plastic or polymide or non\$2conduct\$8 or insulat\$8 or epoxy)) and ((plate or board or substrate or article) near5 (via\$3 or hole\$3 or opening\$3 or trench\$3 or recess\$3 or cavit\$6))) and (electroless\$3 near15 (via\$3 or hole\$3 or opening\$3 or trench\$3 or recess\$3 or cavit\$6))) and ((electroplat\$10 or electrodeposit\$10 or electroly\$10 or electrochem\$10) near15 (via\$3 or hole\$3 or opening\$3 or trench\$3 or recess\$3 or cavit\$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03
6	498	1	DERWENT; IBM_TDB	2003/09/03
7	135		DERWENT; IBM_TDB	2003/09/03

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9	11419	solder adj balls	USPAT;	2003/09/03
	11719		US-PGPUB;	12:06
			EPO; JPO;	
			DERWENT; IBM TDB	
10	4372	((plate or board or substrate or article)	USPAT;	2003/09/03
10	13/2	near5 (resin\$5 or polymer\$5 or plastic or	US-PGPUB;	12:07
		polyimide or non\$2conduct\$8 or insulat\$8	EPO; JPO;	
		or epoxy)) and (solder adj balls)	DERWENT;	
, ,	4000	(((plate or board or substrate or	<pre>IBM_TDB USPAT;</pre>	2003/09/03
11	4009	article) near5 (resin\$5 or polymer\$5 or	US-PGPUB;	12:07
		plastic or polyimide or non\$2conduct\$8 or	EPO; JPO;	•
		insulat\$8 or epoxy)) and (solder adj	DERWENT;	
		balls)) and (via\$3 or trench\$3 or hole\$3 or opening\$3 or recess\$3 or groove\$3 or	IBM_TDB	
		cavit\$8)		
12	1799	((((plate or board or substrate or	USPAT;	2003/09/03
		article) near5 (resin\$5 or polymer\$5 or	US-PGPUB;	12:09
		plastic or polyimide or non\$2conduct\$8 or	EPO; JPO; DERWENT;	
		insulat\$8 or epoxy)) and (solder adj balls)) and (via\$3 or trench\$3 or hole\$3	IBM TDB	
		or opening\$3 or recess\$3 or groove\$3 or	1211_122	
		cavit\$8)) and wiring		
13	1496		USPAT;	2003/09/03
		article) near5 (resin\$5 or polymer\$5 or plastic or polyimide or non\$2conduct\$8 or	US-PGPUB; EPO; JPO;	12:00
		insulat\$8 or epoxy)) and (solder adj	DERWENT;	
		balls)) and (via\$3 or trench\$3 or hole\$3	IBM_TDB	
		or opening\$3 or recess\$3 or groove\$3 or		
1		cavit\$8)) and wiring) and pad\$3	USPAT;	2003/09/03
15	93	<pre>((((((plate or board or substrate or article) near5 (resin\$5 or polymer\$5 or</pre>	US-PGPUB;	12:09
1		plastic or polyimide or non\$2conduct\$8 or	EPO; JPO;	
		insulat\$8 or epoxy)) and (solder adj	DERWENT;	
		balls)) and (via\$3 or trench\$3 or hole\$3	IBM_TDB	
		or opening\$3 or recess\$3 or groove\$3 or cavit\$8)) and wiring) and pad\$3) and		
1		(press\$2forming or (injection adj		
		mold\$5))		
16	90	(((((((plate or board or substrate or	USPAT;	2003/09/03
		article) near5 (resin\$5 or polymer\$5 or	US-PGPUB; EPO; JPO;	12:09
		plastic or polyimide or non\$2conduct\$8 or insulat\$8 or epoxy)) and (solder adj	DERWENT;	
1.		balls)) and (via\$3 or trench\$3 or hole\$3	IBM_TDB	
		or opening\$3 or recess\$3 or groove\$3 or		
		cavit\$8)) and wiring) and pad\$3) and	,	
		<pre>(press\$2forming or (injection adj mold\$5))) not ((((((plate or board or</pre>		
ŀ		substrate or article) near5 (resin\$5 or		•
		polymer\$5 or plastic or polyimide or		
		non\$2conduct\$8 or insulat\$8 or epoxy))		
		and ((plate or board or substrate or article) near5 (via\$3 or hole\$3 or		
		opening\$3 or trench\$3 or recess\$3 or		
		cavit\$6))) and (electroless\$3 near15		
		(via\$3 or hole\$3 or opening\$3 or trench\$3		
		or recess\$3 or cavit\$6))) and ((electroplat\$10 or electrodeposit\$10 or		
1	1	electropiats10 or electrodeposits10 or electrodeposits10 or electrochem\$10) near15		
		(via\$3 or hole\$3 or opening\$3 or trench\$3		
		or recess\$3 or cavit\$6))) and wiring) and		
		polish\$10)	L	<u> </u>